EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S224	5	(barrier and Sn$1Ag$1Cu and reflow$3).clm.	US-PGPUB	OR	ON	2008/01/21 18:39
S223	1	(reaction and barrier and Sn$1Ag$1Cu and reflow$3).clm.	US-PGPUB	OR	ON	2008/01/21 18:39
S222	2	(reaction and barrier and solder$3 and reflow$3).clm.	US-PGPUB	OR	ON	2008/01/21 18:39
S221	1	(reaction and barrier and solder$3 and Sn$1Ag$1Cu and reflow$3). clm.	US-PGPUB	OR	ON	2008/01/21 18:38
S220	3	(adhesion and solder$3 and Sn$1Ag$1Cu and reflow$3).clm.	US-PGPUB	OR	ON	2008/01/21 18:38
S219	34	((method or process) and solder$3 and Sn$1Ag$1Cu and reflow$3). clm.	US-PGPUB	OR	ON	2008/01/21 18:38
S218	16	S214 AND Sn$1Ag$1Cu with reflow$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 18:35
S217	50	S214 AND Sn$1Ag$1Cu	USPAT	OR	ON	2008/01/21 18:32
S216	41	(cap or capping) with layer with (sputtering plating evaporation) and S214	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 18:26
S215	19	(cap or capping) with layer with (sputtering plating evaporation) and S214	USPAT	OR	ON	2008/01/21 18:24
S214	9478	S210 S211 S212 S213	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 18:22
S213	4137	(438/106).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:21
S212	1674	(438/123).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:21

EAST Search History

S21 1	1831	(438/613).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:21
S21 0	3079	(438/612).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:21
S20 9	327	(438/611).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 18:21
S20 8	2	"6,143,588".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S20 7	1	S206 and copper	USPAT; DERWENT	OR	ON	2008/01/21 17:53
S20 6	2	(US-7081404-$).did. or (WO-2004075265-$).did.	USPAT; DERWENT	OR	ON	2008/01/21 17:53
S20 5	1	tin near1 "95" near antimony	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S20 4	1737	tin near2 bismuth near antimony	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S20 3	1	tin near2 bismuth near antimonium	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S20 2	104	tin near2 bismuth near eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53

EAST Search History

S20 1	128	tin near2 silver near eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S20 0	2	"20050224966".PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S19 9	2	"7081404".PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S19 8	35	("4185318"|"4527259"|"4554643"|"4868632"|"5357134"|"5408115"|"5467308"|"5763308"|"5768192"|"5859459"|"5877523"|"5923978"|"6348387"|"6424002"|"6563151"|"6624465").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S19 7	65	S196 not S195	USPAT	OR	ON	2008/01/21 17:53
S19 6	96	solder with wettable with (sputtering plating evaporation)	USPAT	OR	ON	2008/01/21 17:53
S19 5	31	solder with wettable with (sputtering plating evaporation) and "438"/$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S19 4	2	(sn tin) with plating with low with cost and "438"/$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S19 3	1	(sn) with plating with low with cost and "438"/$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S19 2	42	(gold au) with plating with cost and "438"/$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S19 1	27	metal with deposit$5 with (sputtering plating evaporation) with cost and "438"/$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S19 0	1414039	metal deposit$5 with (sputtering plating evaporation) with cost and "438"/$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S18 9	2	metal near2 layer with deposit$5 with (sputtering plating evaporation) with cost and "438"/$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S18 8	0	(ball c4 bump flip solder near2 ball) same metal near2 layer with deposit$5 with (sputtering plating evaporation) with cost and "438"/$.ccls.	USPAT	OR	ON	2008/01/21 17:53

S18 7	5	(ball c4 bump flip solder near2 ball) same (cap or capping) with layer with (sputtering plating evaporation) and "438"/$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S18 6	350	(cap or capping) with layer with (sputtering plating evaporation) and "438"/$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S18 5	5	(cap or capping) with layer with (sputtering plating evaporation) and 257/737.ccls.	USPAT	OR	ON	2008/01/21 17:53
S18 4	860	(cap or capping) with layer with (sputtering plating evaporation)	USPAT	OR	ON	2008/01/21 17:53
S18 3	1	"5,234,149".pn. and (cap capping)	USPAT	OR	ON	2008/01/21 17:53
S18 2	1	"5532612".pn. and anneal$5 with minutes	USPAT	OR	ON	2008/01/21 17:53
S18 1	1	"5532612".pn. and anneal$5	USPAT	OR	ON	2008/01/21 17:53
S18 0	31	(bump solder near2 ball) with anneal$5 and anneal$5 with (min minutes hour second)	USPAT	OR	ON	2008/01/21 17:53
S17 9	106	(bump solder near2 ball) with anneal$5	USPAT	OR	ON	2008/01/21 17:53
S17 8	11	(bump solder near2 ball) with anneal$5 with (min minutes hour second)	USPAT	OR	ON	2008/01/21 17:53
S17 7	2	(bump solder near2 ball) with anneal$5 with minutes	USPAT	OR	ON	2008/01/21 17:53
S17 6	4	wettable with layer with (copper cu) and pure near2 (tin sn) with (bump ball c4)	USPAT	OR	ON	2008/01/21 17:53
S17 5	200	wettable with layer with (copper cu)	USPAT	OR	ON	2008/01/21 17:53
S17 4	2	tin with bump same cu with wett$6	USPAT	OR	ON	2008/01/21 17:53
S17 3	0	tin with bump with cu with wettable	USPAT	OR	ON	2008/01/21 17:53
S17 2	1	"5,234,149".pn.	USPAT	OR	ON	2008/01/21 17:53
S17 1	210	wettable with (layer film) with (gold au)	USPAT	OR	ON	2008/01/21 17:53
S17 0	2	final with wettable with (layer film) with (gold au)	USPAT	OR	ON	2008/01/21 17:53
S16 9	58	bump with plating with seed with layer	USPAT	OR	ON	2008/01/21 17:53
S16 8	64	bump same (au gold) with wetting	USPAT	OR	ON	2008/01/21 17:53
S16 7	5	au with bump with plating with seed	USPAT	OR	ON	2008/01/21 17:53

S16 6	6	gold with bump with plating with seed	USPAT	OR	ON	2008/01/21 17:53
S16 5	23182	gold with bump wit plating with seed	USPAT	OR	ON	2008/01/21 17:53
S16 4	12	barrier with wetting with layer with au	USPAT	OR	ON	2008/01/21 17:53
S16 3	113	barrier with au with bump	USPAT	OR	ON	2008/01/21 17:53
S16 2	1	barrier with au with wettab$5 with bump	USPAT	OR	ON	2008/01/21 17:53
S16 1	35	S159 and 257/737.ccls.	USPAT	OR	ON	2008/01/21 17:53
S16 0	71	S159 and 257/737.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S15 9	788	(BLM UBM) with (ti tin ta tan zr znn v ni)	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S15 8	10	(BLM UBM) with adhesion with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S15 7	2	("20020137325" | "6492197").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S15 6	47	"438"/$.ccls. and (Pb lead) near2 free and (BLM UBM) and sputtering	USPAT	OR	ON	2008/01/21 17:53
S15 5	30	S154 and (Pb lead) near2 free and (BLM UBM)	USPAT	OR	ON	2008/01/21 17:53
S15 4	2330	(438/614).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 17:53
S15 3	2	S152 and lead near2 free	USPAT	OR	ON	2008/01/21 17:53
S15 2	8	("4835593"|"5162257"|"5244143"|"5 767010"|"5775569"|"5937320"|"600 3757"|"6056191").PN.	USPAT	OR	ON	2008/01/21 17:53
S15 1	2	"20050224966".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S15 0	16	("4835593"|"5162257"|"5244143"|"5 767010"|"5775569"|"5937320"|"600 3757"|"6056191").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53

S149	177	andujar.xp.	USPAT	OR	ON	2008/01/21 17:53
S148	184	(armando with rodriguez).xp.	USPAT	OR	ON	2008/01/21 17:53
S147	359	(armando with rodriguez).xa.	USPAT	OR	ON	2008/01/21 17:53
S146	309	((flores or ruiz) with delma).xa.	USPAT	OR	ON	2008/01/21 17:53
S145	31	epoxy near1 resin with commonly with used with (reliability moldability, moisture absorbing resistance adhesion)	USPAT	OR	ON	2008/01/21 17:53
S144	29	S143 and "257"$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S143	88	encapsulat$3 with epoxy with prefer$5	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S142	2664	S141 and "257"$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S141	11490	encapsulat$3 with epoxy	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S140	37	S139 and "257"$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S139	103	encapsulat$3 with epoxy with cost	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S138	34	S135 and "257"$.ccls.	USPAT	OR	ON	2008/01/21 17:53
S137	59	S135 and "257"$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S136	0	S135 and 257/797.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S135	134	molding with epoxy with cost	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S134	1	"6114752".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S133	34	"6114752"	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S132	12	("4884124" | "5223740" | "5233222" | "5264730" | "5327008" | "5521428" | "5550402" | "5661338" | "5683944" | "5723897" | "5963782" | "6049120").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53

S13 1	4	("5140404" | "5491362" | "6114752" | "6191490").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S13 0	35	("4258381" | "4857989" | "5214307").PN. OR ("6114752"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S12 9	8	("5140404" | "5491362" | "6114752" | "6191490").PN. OR ("6440779"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S12 8	35	("4258381" | "4857989" | "5214307").PN. OR ("6114752"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S12 7	12	("4532222"|"5986209"|"6114752"|"6424031"|"6504238"|"6638790").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S12 6	171	S124 and S125	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S12 5	10264	(257/666-677).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 17:53
S12 4	2258	(chip IC die) with pad with ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S12 3	204	(chip IC die) with pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S12 2	5630	pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S12 1	11	S120 not S115	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53

S12 0	21	S119 and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S11 9	10264	(257/666-677).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 17:53
S11 8	309036	"257"/(666-677).ccls. and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S11 7	309036	"257"/(666-677).ccls. and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S11 6	309036	"257"(666-677).ccls. and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S11 5	10	S114 and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR.	ON	2008/01/21 17:53
S11 4	2706	(257/676).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2008/01/21 17:53
S11 3	1	"6373127".pn. and tape	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53

S11 2	71	("20030073265" | "3838984" | "4530152" | "4707724" | "4756080" | "4812896" | "5041902" | "5157480" | "5172213" | "5172214" | "5200362" | "5200809" | "5214845" | "5216278" | "5221642" | "5258094" | "5273938" | "5277972" | "5278446" | "5279029" | "5332864" | "5336931" | "5343076" | "5391439" | "5406124" | "5424576" | "5435057" | "5521429" | "5604376" | "5608267" | "5639990" | "5640047" | "5641997" | "5646831" | "5650663" | "5683806" | "5696666" | "5701034" | "5710064" | "5736432" | "5776798" | "5783861" | "5835988" | "5859471" | "5866939" | "5877043" | "5894108" | "5977613" | "5977630" | "5981314" | "6001671" | "6018189" | "6025640" | "6130115" | "6130473" | "6143981" | "6198171" | "6225146" | "6229200" | "6242281" | "6281568" | "6437429" | "6448633" | "6483178" | "6545332" | "6580161" | "6611047" | "6700189" | "6861734").PN. OR ("7042068"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S11 1	135	("5172214" | "5521429").PN. OR ("5977613").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S11 0	84	("3838984" | "4530152" | "4707724" | "4756080" | "4812896" | "5041902" | "5157480" | "5172213" | "5172214" | "5200362" | "5200809" | "5214845" | "5216278" | "5221642" | "5258094" | "5273938" | "5277972" | "5278446" | "5279029" | "5332864" | "5336931" | "5343076" | "5406124" | "5424576" | "5435057" | "5474958" | "5521429" | "5604376" | "5608267" | "5639990" | "5640047" | "5641997" | "5646831" | "5650663" | "5683806" | "5696666" | "5701034" | "5710064" | "5776798" | "5783861" | "5835988" | "5859471" | "5866939" | "5877043" | "5894108" | "5977613" | "5977615" | "5977630" | "5981314" | "6001671" | "6025640" | "6130115" | "6130473" | "6143981" | "6198171" | "6225146" | "6229200" | "6242281" | "6281568").PN. OR ("6455356").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S10 9	65	("5270491" | "5529959" | "5811799" | "5898218" | "6191359" | "6208020" | "6303978" | "6355502").PN. OR ("6476469").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53

S108	25	("20010030355" | "20010042904" | "20020041011" | "20020079561" | "20020121684" | "20020153597" | "20030001244" | "20030006492" | "20030042581" | "20030073265" | "4283839" | "5466966" | "6025640" | "6075284" | "6078098" | "6081029" | "6166430" | "6211462" | "6229200" | "6448633" | "6455356" | "6462424" | "6476469" | "6521987" | "6700186").PN. OR ("6979886").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/21 17:53
S107	11	("0127711"|"6504238"|"6828661"|"6900524"|"6979886").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/21 17:53
S106	2	"6,143,588".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 19:01
S105	1	S104 and copper	USPAT; DERWENT	OR	ON	2007/09/28 17:20
S104	2	(US-7081404-$).did. or (WO-2004075265-$).did.	USPAT; DERWENT	OR	ON	2007/09/28 17:20
S103	1	tin near1 "95" near antimony	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 16:32
S102	1712	tin near2 bismuth near antimony	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 16:27
S101	1	tin near2 bismuth near antimonium	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 16:25
S100	99	tin near2 bismuth near eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 16:24

S99	121	tin near2 silver near eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 16:20
S98	2	"20050224966".PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 16:17
S97	2	"7081404".PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2007/09/28 16:09
S96	35	("4185318"|"4527259"|"4554643"|"4868632"|"5357134"|"5408115"|"5467308"|"5763308"|"5768192"|"5859459"|"5877523"|"5923978"|"6348387"|"6424002"|"6563151"|"6624465").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/30 11:41
S95	62	S94 not S93	USPAT	OR	ON	2006/10/28 18:29
S94	88	solder with wettable with (sputtering plating evaporation)	USPAT	OR	ON	2006/10/28 18:29
S93	26	solder with wettable with (sputtering plating evaporation) and "438"/$.ccls.	USPAT	OR	ON	2006/10/28 18:29
S92	2	(sn tin) with plating with low with cost and "438"/$.ccls.	USPAT	OR	ON	2006/10/28 18:24
S91	1	(sn) with plating with low with cost and "438"/$.ccls.	USPAT	OR	ON	2006/10/28 18:24
S90	40	(gold au) with plating with cost and "438"/$.ccls.	USPAT	OR	ON	2006/10/28 18:24
S89	22	metal with deposit$5 with (sputtering plating evaporation) with cost and "438"/$.ccls.	USPAT	OR	ON	2006/10/28 18:22
S88	1344965	metal deposit$5 with (sputtering plating evaporation) with cost and "438"/$.ccls.	USPAT	OR	ON	2006/10/28 18:21
S87	1	metal near2 layer with deposit$5 with (sputtering plating evaporation) with cost and "438"/$.ccls.	USPAT	OR	ON	2006/10/28 18:21
S86	0	(ball c4 bump flip solder near2 ball) same metal near2 layer with deposit$5 with (sputtering plating evaporation) with cost and "438"/$.ccls.	USPAT	OR	ON	2006/10/28 18:20

S85	4	(ball c4 bump flip solder near2 ball) same (cap or capping) with layer with (sputtering plating evaporation) and "438"/$.ccls.	USPAT	OR	ON	2006/10/28 18:19
S84	290	(cap or capping) with layer with (sputtering plating evaporation) and "438"/$.ccls.	USPAT	OR	ON	2006/10/28 18:18
S83	5	(cap or capping) with layer with (sputtering plating evaporation) and 257/737.ccls.	USPAT	OR	ON	2006/10/28 18:16
S82	737	(cap or capping) with layer with (sputtering plating evaporation)	USPAT	OR	ON	2006/10/28 18:16
S81	1	"5,234,149".pn. and (cap capping)	USPAT	OR	ON	2006/10/28 18:15
S80	1	"5532612".pn. and anneal$5 with minutes	USPAT	OR	ON	2006/10/28 18:13
S79	1	"5532612".pn. and anneal$5	USPAT	OR	ON	2006/10/28 18:04
S75	2	(bump solder near2 ball) with anneal$5 with minutes	USPAT	OR	ON	2006/10/28 18:03
S78	29	(bump solder near2 ball) with anneal$5 and anneal$5 with (min minutes hour second)	USPAT	OR	ON	2006/10/28 17:45
S77	94	(bump solder near2 ball) with anneal$5	USPAT	OR	ON	2006/10/28 17:44
S76	10	(bump solder near2 ball) with anneal$5 with (min minutes hour second)	USPAT	OR	ON	2006/10/28 17:44
S74	4	wettable with layer with (copper cu) and pure near2 (tin sn) with (bump ball c4)	USPAT	OR	ON	2006/10/28 17:40
S73	191	wettable with layer with (copper cu)	USPAT	OR	ON	2006/10/28 17:06
S72	2	tin with bump same cu with wett$6	USPAT	OR	ON	2006/10/28 17:04
S71	0	tin with bump with cu with wettable	USPAT	OR	ON	2006/10/28 17:04
S70	1	"5,234,149".pn.	USPAT	OR	ON	2006/10/28 17:03
S69	180	wettable with (layer film) with (gold au)	USPAT	OR	ON	2006/10/28 16:09
S68	2	final with wettable with (layer film) with (gold au)	USPAT	OR	ON	2006/10/28 16:04
S67	52	bump with plating with seed with layer	USPAT	OR	ON	2006/10/28 16:03
S66	54	bump same (au gold) with wetting	USPAT	OR	ON	2006/10/28 15:58
S65	4	au with bump with plating with seed	USPAT	OR	ON	2006/10/28 15:52
S64	6	gold with bump with plating with seed	USPAT	OR	ON	2006/10/28 15:50
S63	21062	gold with bump wit plating with seed	USPAT	OR	ON	2006/10/28 15:47
S62	12	barrier with wetting with layer with au	USPAT	OR	ON	2006/10/28 15:46
S61	103	barrier with au with bump	USPAT	OR	ON	2006/10/28 15:45

S60	1	barrier with au with wettab$5 with bump	USPAT	OR	ON	2006/10/28 15:43
S59	31	S57 and 257/737.ccls.	USPAT	OR	ON	2006/10/28 15:41
S58	58	S57 and 257/737.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/28 15:27
S57	651	(BLM UBM) with (ti tin ta tan zr znn v ni)	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/28 15:26
S56	8	(BLM UBM) with adhesion with thickness	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/28 15:25
S55	2	("20020137325" | "6492197").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/28 15:06
S54	29	"438"/$.ccls. and (Pb lead) near2 free and (BLM UBM) and sputtering	USPAT	OR	ON	2006/10/28 13:59
S53	24	S52 and (Pb lead) near2 free and (BLM UBM)	USPAT	OR	ON	2006/10/28 13:58
S52	2223	(438/614).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/28 13:54
S51	2	S50 and lead near2 free	USPAT	OR	ON	2006/10/28 13:54
S50	8	("4835593"|"5162257"|"5244143"|"5767010"|"5775569"|"5937320"|"6003757"|"6056191").PN.	USPAT	OR	ON	2006/10/28 13:53
S48	16	("4835593"|"5162257"|"5244143"|"5767010"|"5775569"|"5937320"|"6003757"|"6056191").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/28 13:52
S49	2	"20050224966".pn.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/28 13:23
S47	42	andujar.xp.	USPAT	OR	ON	2006/10/24 16:14
S46	61	(armando with rodriguez).xp.	USPAT	OR	ON	2006/10/24 16:11
S45	359	(armando with rodriguez).xa.	USPAT	OR	ON	2006/10/24 16:11
S44	283	((flores or ruiz) with delma).xa.	USPAT	OR	ON	2006/10/24 16:10
S43	29	epoxy near1 resin with commonly with used with (reliability moldability, moisture absorbing resistance adhesion)	USPAT	OR	ON	2006/10/24 16:10
S39	25	S38 and "257"$.ccls.	USPAT	OR	ON	2006/10/24 15:11

S38	77	encapsulat$3 with epoxy with prefer$5	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 15:09
S37	2386	S36 and "257"$.ccls.	USPAT	OR	ON	2006/10/24 15:09
S36	10021	encapsulat$3 with epoxy	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 15:08
S35	31	S34 and "257"$.ccls.	USPAT	OR	ON	2006/10/24 15:08
S34	90	encapsulat$3 with epoxy with cost	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 15:08
S33	32	S30 and "257"$.ccls.	USPAT	OR	ON	2006/10/24 15:06
S30	122	molding with epoxy with cost	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 15:06
S32	48	S30 and "257"$.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 15:01
S31	0	S30 and 257/797.ccls.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 15:01
S29	1	"6114752".pn.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 15:00
S28	24	"6114752"	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 14:53
S27	12	("4884124" | "5223740" | "5233222" | "5264730" | "5327008" | "5521428" | "5550402" | "5661338" | "5683944" | "5723897" | "5963782" | "6049120").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 14:53
S26	4	("5140404" | "5491362" | "6114752" | "6191490").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 14:37
S25	25	("4258381" | "4857989" | "5214307").PN. OR ("6114752"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 10:46
S24	8	("5140404" | "5491362" | "6114752" | "6191490").PN. OR ("6440779"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 10:45
S23	25	("4258381" | "4857989" | "5214307").PN. OR ("6114752"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/24 10:43
S22	12	("4532222"|"5986209"|"6114752"|"6424031"|"6504238"|"6638790").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 10:42

S21	148	S19 and S20	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 10:04
S20	9559	(257/666-677).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/24 10:04
S19	1986	(chip IC die) with pad with ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 10:04
S18	182	(chip IC die) with pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/24 10:04
S17	5273	pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 15:05
S16	11	S15 not S10	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 15:04
S15	18	S14 and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 15:04
S14	9553	(257/666-677).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 15:04
S13	282813	"257"/(666-677).ccls. and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 15:04

EAST Search History

S12	282813	"257"/(666-677).ccls. and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 15:03
S11	282813	"257"(666-677).ccls. and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 15:02
S10	7	S8 and pad with rim	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 15:02
S8	2477	(257/676).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2006/10/23 15:00
S7	1	"6373127".pn. and tape	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/23 14:59
S6	69	("20030073265" | "3838984" | "4530152" | "4707724" | "4756080" | "4812896" | "5041902" | "5157480" | "5172213" | "5172214" | "5200362" | "5200809" | "5214845" | "5216278" | "5221642" | "5258094" | "5273938" | "5277972" | "5278446" | "5279029" | "5332864" | "5336931" | "5343076" | "5391439" | "5406124" | "5424576" | "5435057" | "5521429" | "5604376" | "5608267" | "5639990" | "5640047" | "5641997" | "5646831" | "5650663" | "5683806" | "5696666" | "5701034" | "5710064" | "5736432" | "5776798" | "5783861" | "5835988" | "5859471" | "5866939" | "5877043" | "5894108" | "5977613" | "5977630" | "5981314" | "6001671" | "6018189" | "6025640" | "6130115" | "6130473" | "6143981" | "6198171" | "6225146" | "6229200" | "6242281" | "6281568" | "6437429" | "6448633" | "6483178" | "6545332" | "6580161" | "6611047" | "6700189" | "6861734").PN. OR ("7042068").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/23 14:42
S5	116	("5172214" | "5521429").PN. OR ("5977613").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/23 14:03

EAST Search History

S4	77	("3838984" | "4530152" | "4707724" | "4756080" | "4812896" | "5041902" | "5157480" | "5172213" | "5172214" | "5200362" | "5200809" | "5214845" | "5216278" | "5221642" | "5258094" | "5273938" | "5277972" | "5278446" | "5279029" | "5332864" | "5336931" | "5343076" | "5406124" | "5424576" | "5435057" | "5474958" | "5521429" | "5604376" | "5608267" | "5639990" | "5640047" | "5641997" | "5646831" | "5650663" | "5683806" | "5696666" | "5701034" | "5710064" | "5776798" | "5783861" | "5835988" | "5859471" | "5866939" | "5877043" | "5894108" | "5977613" | "5977615" | "5977630" | "5981314" | "6001671" | "6025640" | "6130115" | "6130473" | "6143981" | "6198171" | "6225146" | "6229200" | "6242281" | "6281568").PN. OR ("6455356").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/23 13:55
S3	45	("5270491" | "5529959" | "5811799" | "5898218" | "6191359" | "6208020" | "6303978" | "6355502").PN. OR ("6476469").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/23 13:51
S2	25	("20010030355" | "20010042904" | "20020041011" | "20020079561" | "20020121684" | "20020153597" | "20030001244" | "20030006492" | "20030042581" | "20030073265" | "4283839" | "5466966" | "6025640" | "6075284" | "6078098" | "6081029" | "6166430" | "6211462" | "6229200" | "6448633" | "6455356" | "6462424" | "6476469" | "6521987" | "6700186").PN. OR ("6979886").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/10/23 13:49
S1	11	("0127711"|"6504238"|"6828661"|"6900524"|"6979886").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/10/23 13:48